GENERAL PROPERTIES

	PROPERTY	TYPICAL VALUE	DIRECTION	CONDITION	TEST METHOD
Thermal	Glass Transition Temperature, Tg	200	°C	A	DMA IPC-TM-650 2.4.24.2
		190	°C	A	DSC IPC-TM650 2.4.25
	Thermal Expansion, Z CTE	45	ppm/°C	A	Before Tg, IPC-TM-650 2.4.41
		210	ppm/°C	A	After Tg, IPC-TM-650 2.4.41
	Decomposition Temperature, Td	350	°C	A	TMA IPC-TM650 2.4.24.6
	Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24.1
	Delamination Time, T288	45	minutes	A	TMA IPC-TM650 2.4.24.1
Electrical	Dielectric Constant (Dk)	4.6	-	1 GHz	IPC-TM-650 2.5.5.9
		4.8	-	1 MHz	IPC-TM-650 2.5.5.9
	Dissipation Factor (Df)	0.015	-	1 GHz	IPC-TM-650 2.5.5.9
		0.009	-	1 MHz	IPC-TM-650 2.5.5.9
	Volume Resistivity	2.51E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
	Surface Resistivity	3.29E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
	Dielectric Breakdown	65	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Physical	Thermal Conductivity	0.53	W/m·K	100°C	ASTM D5470
	Water Absorption	0.12	%	D-24/23	IPC-TM-650 2.6.2.1
	Copper Peel Strength	1.25 (7.1)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
	Flammability	94V-0	-	A	UL

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